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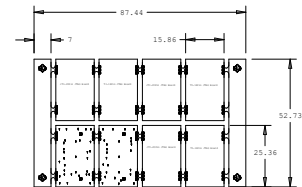
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FABRICATION NOTES:

1. FABRICATE PCB IN ACCORDANCE WITH IPC-6012D, CLASS 2 PER IPC-6011.
2. MATERIALS:
- 1. LAMINATE AND PREPREG (8-STAGE) TO BE IN ACCORDANCE WITH IPC-4101/126.
(REF TO 170)
 - 2. COPPER FOIL TO BE IN ACCORDANCE WITH IPC-M-98, UNLESS OTHERWISE SPECIFIED,
ALL COPPER WEIGHT FOR OTHER LAYERS TO BE 35UM (1.0Z.).
 - 3. COPPER WEIGHT IS TO BE CONSIDERED "FINISHED".
 - 4. THE COPPER FOIL THICKNESS TOLERANCES SHALL BE AS PER IPC 6012B TABLE NO.3-7 AND 3-8.
3. ALL HOLES SHALL BE LOCATED WITHIN 0.19MM DIAMETER OF THEIR POSITION.
LAYERS TO LAYER REGISTRATION SHALL BE WITHIN 0.12MM.
4. BOM AND TRIST SHALL NOT EXCEED MORE THAN 0.75% OF THE DESIGN LENGTH.
5. CONDUCTOR WIDTH SHALL NOT BE LESS THAN 20% FROM ITS ORIGINAL DATA, INCREASE FOR MATCHING
IMPEDANCE NEUTRAL SHALL AVOID THE MODIFIED WIDTHS AND SPACING.
6. TRACE WIDTH SHALL BE MEASURED ON THE SURFACE IN CONTACT WITH THE LAMINATE.
6. AUTOMATED OPTICAL INSPECTION OF ALL THE LAYERS IS REQUIRED.
7. FINISH:
- 1. ALL EXPOSED CONDUCTIVE PATTERN AREAS NOT COVERED WITH SOLDER MASK OR OTHER PLATING SHALL BE ENIG,
ELECTROLESS NICKEL/IMMERSION GOLD, ELECTROLESS NICKEL SHALL BE 3+6 MICRONS, TYPICAL IMMERSION GOLD
THICKNESS SHALL BE 0.80 (0.031") PER SIDE SHALL BE REDUCED IF IMMERSION GOLD SURFACE.
 - 2. APPLY LIQUID HOT IMAGABLE SOLDER MASK PER IPC-M-400, CLASS 8, TO BOTH SIDES OF THE BOARD OVER SOLDER
VIA. HOLES SHALL BE FILLED WITH NON CONDUCTIVE INK AND COVERED WITH SOLDER MASK. ONLY SOLDER MASK IMAGES
THICKNESS SHALL BE 0.80 (0.031") PER SIDE SHALL BE REDUCED IF IMMERSION GOLD SURFACE.
 - 3. ALL OTHER SOLDER MASK IMAGES SHALL NOT BE ENLARGED. DEFAULT COLOUR OF SOLDER MASK SHALL BE GREEN.
 - 4. SILKSCREEN SHALL BE WHITE, PERMANENT, ORGANIC, NON-CONDUCTIVE INK. THERE SHALL BE
NO SILKSCREEN ON NON SOLDERABLE COMPONENT PAD. CLIPPING OF SILK SCREEN SHALL BE ALLOWED
IF THE SILK SCREEN FALLS ON SOLDERABLE AREA.
 - 5. SURFACE AND VIA HOLES FINISH SHALL NOT BE LESS THAN 200 (0.0007").
8. ALL HOLES SUBSCORBED BY LAND <=0.010" SHALL BE COMPLAIN TO IPC6012, CLASS 2.
8. MARKING:
- 1. BOARD SHALL MEET THE REQUIREMENTS OF UL-796C WITH FLAMMABILITY RATING OF MINIMUM 94V-0. UL LOGO, UL FILE NUMBER,
MANUFACTURER'S IDENTIFICATION AND DATE CODE LETTER SHALL BE REPRODUCED IN SILKSCREEN.
9. TEST REQUIREMENTS:
- 1. 100% NET LIST ELECTRICAL VERIFICATION USING METALLIC SUPPLIED IPC-D-356 NET LIST FOR OPENES AND SHORTS.
 - 2. TRIEVING IS ALLOWED ONLY IN THE PANEL FRAME, NOT IN THE CIRCUIT AREA.
 - 3. TEAR DROPS SHALL BE ADDED ON VIA'S AND THROUGH HOLE PADS IN OTHER LAYERS.
10. FINISHED PCB THICKNESS SHALL BE 0.063+/-0.010.
11. MIN TRACE WIDTH/SPACING ON BOARD IS 0.066"/0.066".



LAYER STACKUP			
LAYER NAME	FINISHED Cu	X-SECTION	DIELECTRIC THICKNESS
PRIMARY SIDE SILKSCREEN			[INCHES]
PRIMARY SIDE SOLDERMASK			
PRIMARY SIDE	1oz.		
SECONDARY SIDE	1oz.		0.063
SECONDARY SIDE SOLDERMASK			
SECONDARY SIDE SILKSCREEN			

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
•	12.0	+3.0/-3.0	PLATED	58
■	32.0	+3.0/-3.0	NON-PLATED	96
●	40.0	+3.0/-3.0	NON-PLATED	4
⊗	126.0	+3.0/-3.0	NON-PLATED	4

SIGNATURES		DATE		 TEXAS INSTRUMENTS		PROC081	
LAYOUT BY JA		080319					
APPROVED BY ZA		080319		J7X PROC081 JTAG ADAPTER BOARD			
APPROVED BY AMB		080319					
		SIZE D		Rev E2			
		SCALE: NONE				SHEET 1 OF 09	